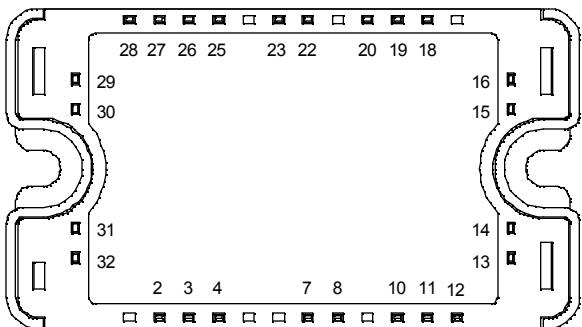
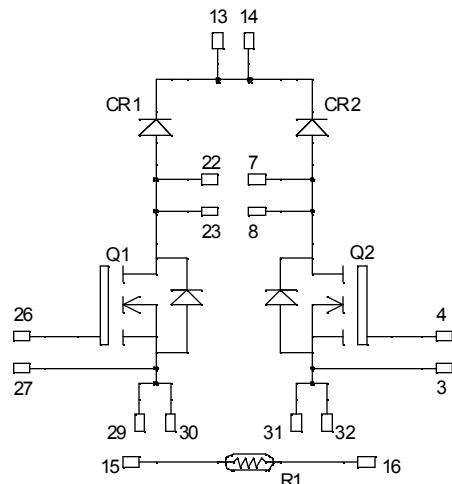


**Dual boost chopper  
Super Junction MOSFET  
Power Module**

**V<sub>DSS</sub> = 600V**  
**R<sub>DSon</sub> = 70mΩ max @ T<sub>j</sub> = 25°C**  
**I<sub>D</sub> = 39A @ T<sub>c</sub> = 25°C**



All multiple inputs and outputs must be shorted together  
Example: 13/14 ; 29/30 ; 22/23 ...

#### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V <sub>DSS</sub>	Drain - Source Breakdown Voltage	600	V
I <sub>D</sub>	Continuous Drain Current	T <sub>c</sub> = 25°C T <sub>c</sub> = 80°C	39 29
I <sub>DM</sub>	Pulsed Drain current		
V <sub>GS</sub>	Gate - Source Voltage	±20	V
R <sub>DSon</sub>	Drain - Source ON Resistance	70	mΩ
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> = 25°C 250	W
I <sub>AR</sub>	Avalanche current (repetitive and non repetitive)	20	A
E <sub>AR</sub>	Repetitive Avalanche Energy	1	mJ
E <sub>AS</sub>	Single Pulse Avalanche Energy	1800	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)



**Thermal and package characteristics**
**Symbol**    **Characteristic**

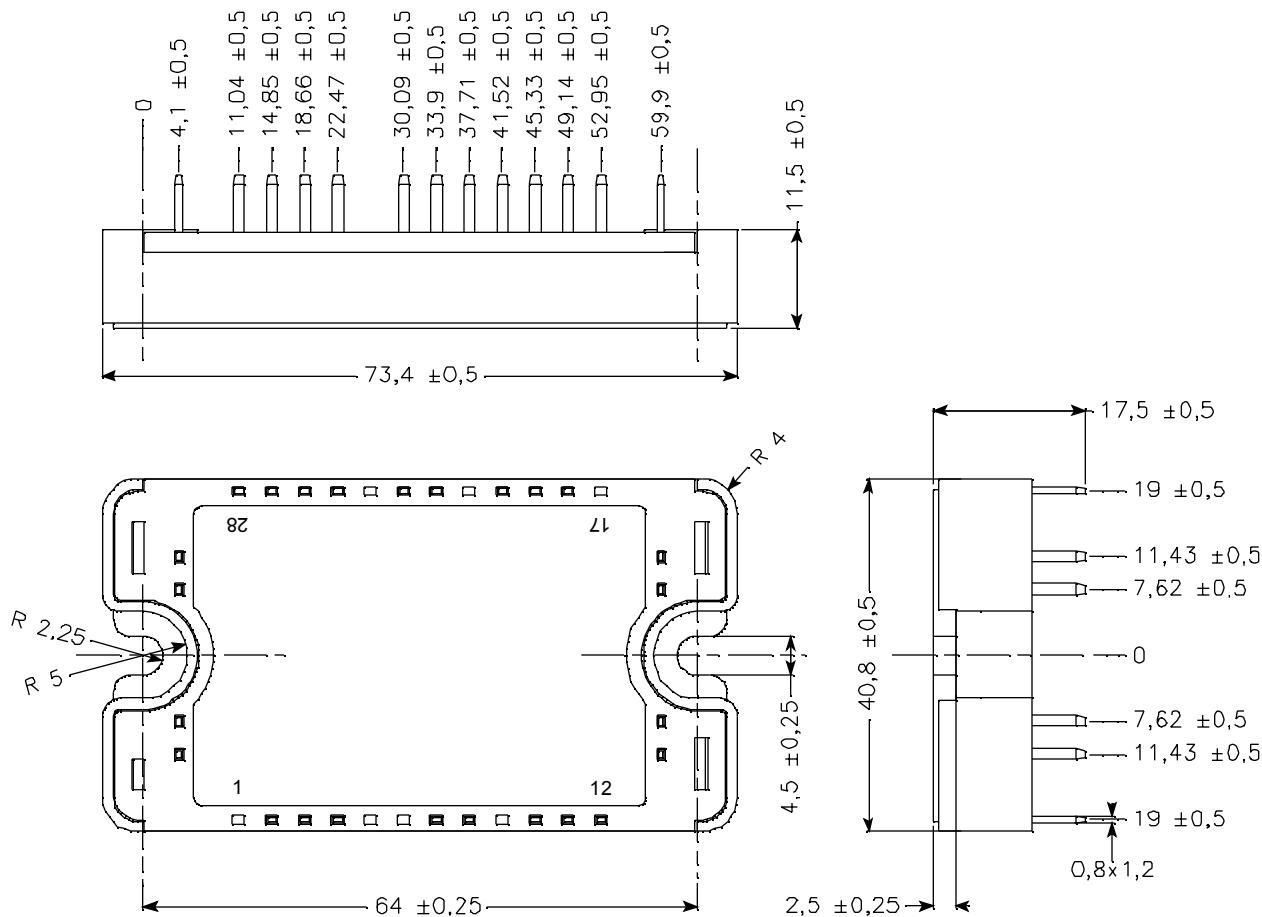
			Min	Typ	Max	Unit
$R_{thJC}$	Junction to Case Thermal Resistance	Transistor			0.5	°C/W
		Diode			1.5	
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case t = 1 min, $I_{isol} < 1mA$ , 50/60Hz	2500				V
$T_J$	Operating junction temperature range	-40		150		
$T_{STG}$	Storage Temperature Range	-40		125		°C
$T_C$	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M4	2.5	4.7	N.m
Wt	Package Weight				110	g

**Temperature sensor NTC** (see application note APT0406 on www.microsemi.com for more information).

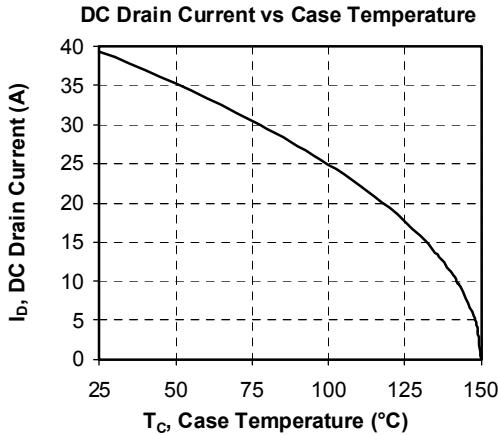
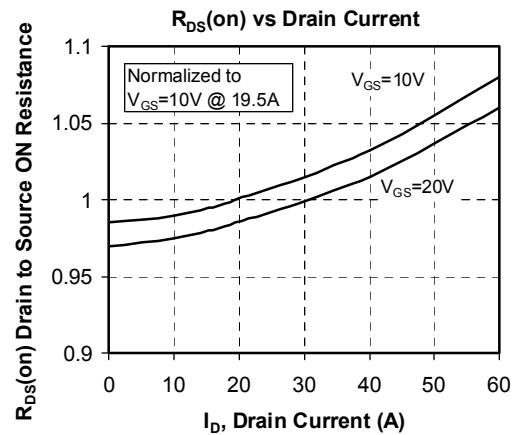
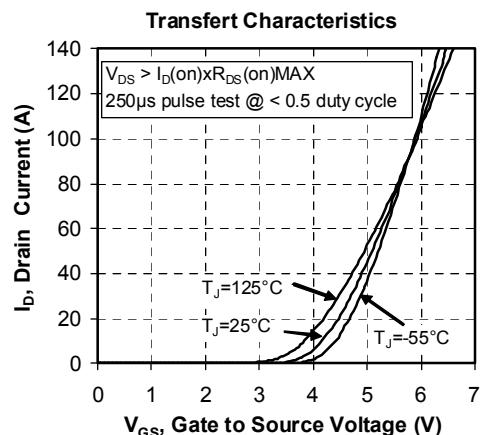
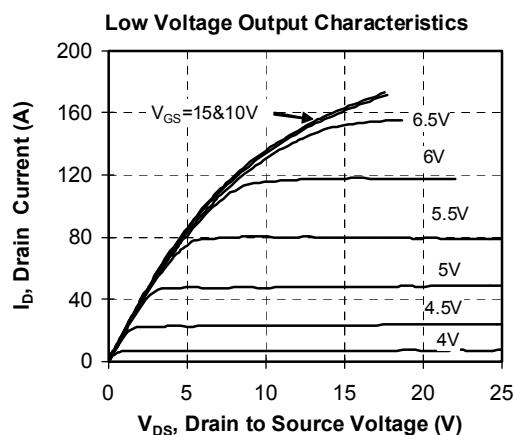
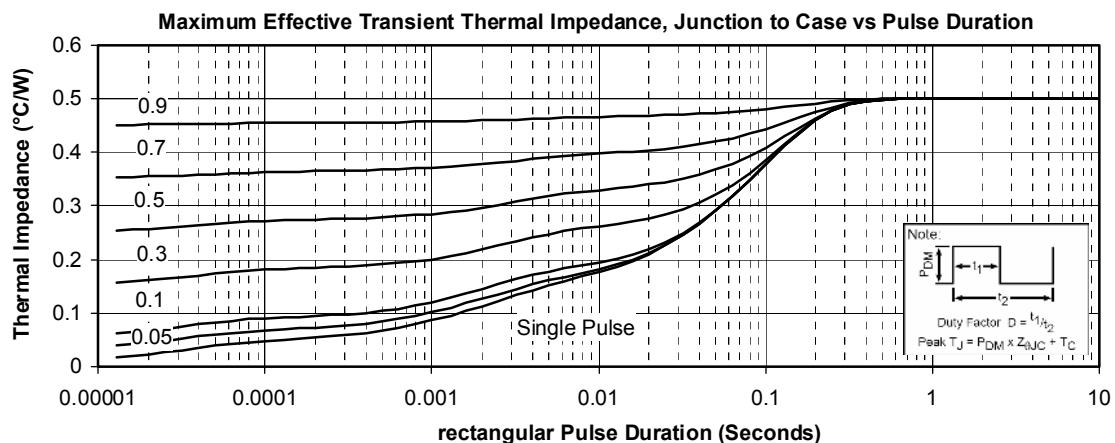
**Symbol**    **Characteristic**

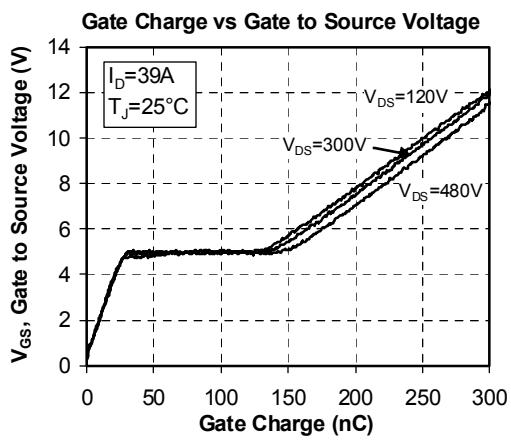
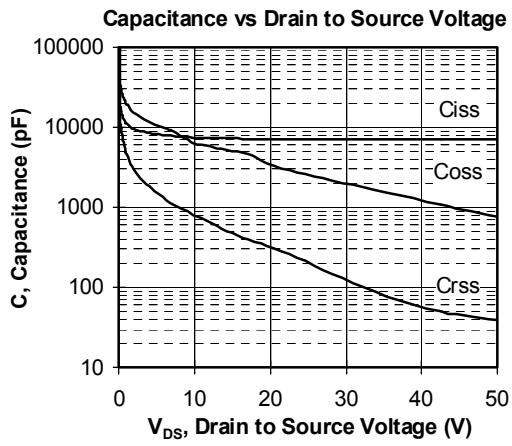
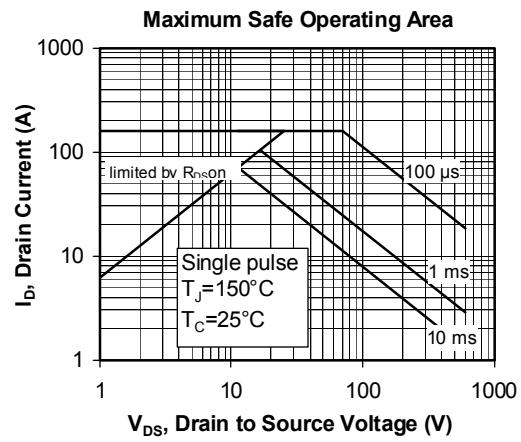
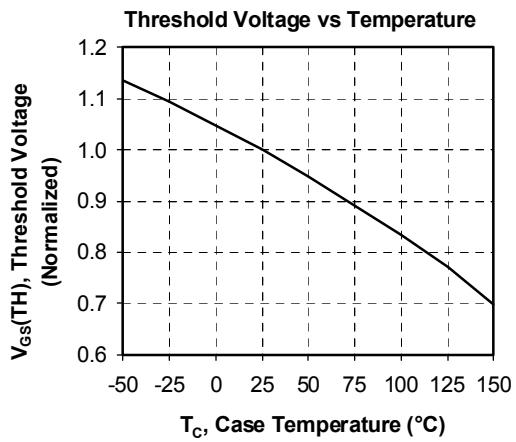
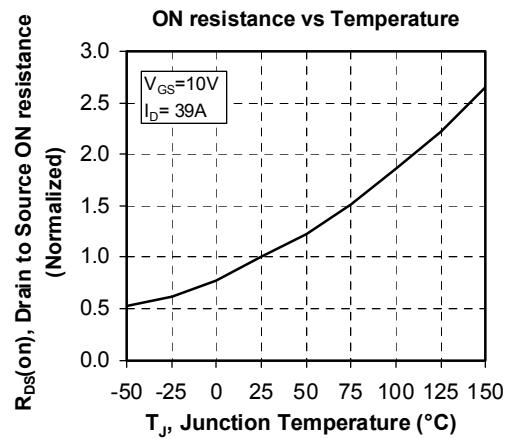
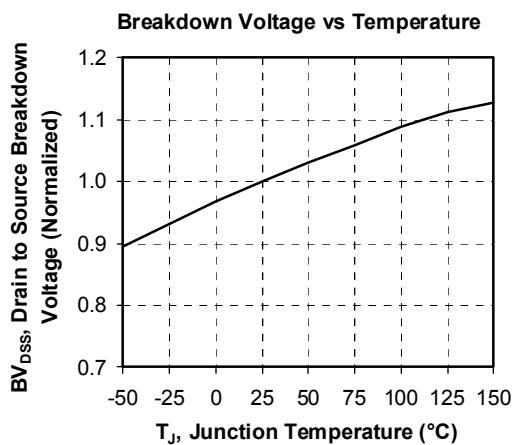
			Min	Typ	Max	Unit
$R_{25}$	Resistance @ 25°C			50		kΩ
$B_{25/85}$	$T_{25} = 298.15 \text{ K}$			3952		K

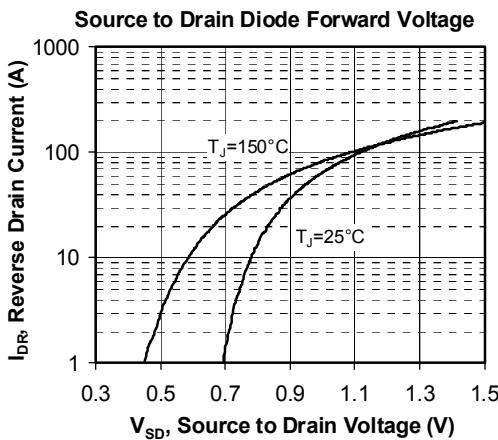
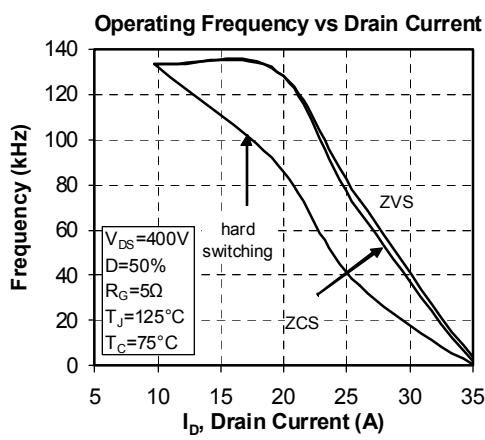
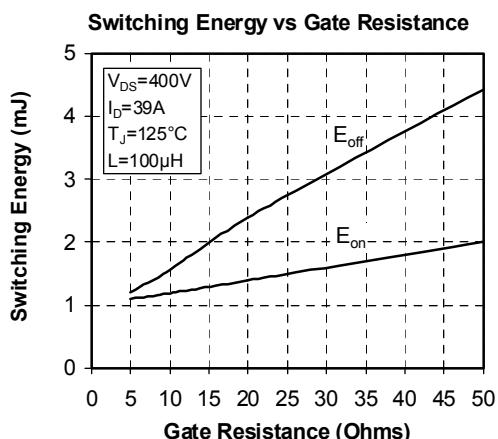
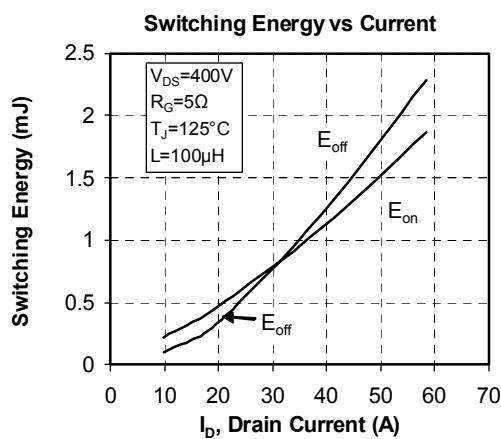
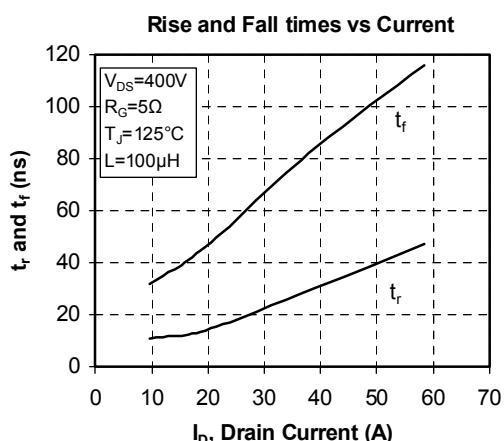
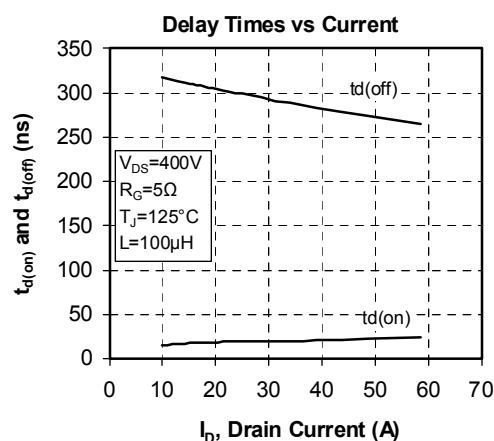
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]} \quad T: \text{ Thermistor temperature } \\ R_T: \text{ Thermistor value at } T$$

**SP3 Package outline (dimensions in mm)**

 See application note 1901 - Mounting Instructions for SP3 Power Modules on [www.microsemi.com](http://www.microsemi.com)

### Typical Performance Curve







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